

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3272620

| | |
|---|---------------------------------------|
| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| | |
| Name | Execution Date |
| HIKARU TADANO | 02/10/2015 |
| YOSUKE KONDO | 03/03/2015 |
| HIROAKI MONMA | 03/03/2015 |
| RECEIVING PARTY DATA | |
| Name: | NOK CORPORATION |
| Street Address: | 12-15 SHIBA DAIMON 1-CHOME, MINATO-KU |
| City: | TOKYO |
| State/Country: | JAPAN |
| Postal Code: | 105-8585 |
| PROPERTY NUMBERS Total: 1 | |
| | |
| Property Type | Number |
| Application Number: | 14429478 |
| CORRESPONDENCE DATA | |
| Fax Number: | (248)641-0270 |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | |
| Email: | draquino@hdp.com, docket@hdp.com |
| Correspondent Name: | HARNESS, DICKEY & PIERCE, PLC |
| Address Line 1: | P.O. BOX 300 |
| Address Line 4: | BLOOMFIELD HILLS, MICHIGAN 48303 |
| ATTORNEY DOCKET NUMBER: | 0702-000054-US-NP |
| NAME OF SUBMITTER: | RYAN W. MASSEY |
| SIGNATURE: | /Ryan W. Massey/ |
| DATE SIGNED: | 03/19/2015 |
| Total Attachments: 2 | |
| source=Assignment#page1.tif | |
| source=Assignment#page2.tif | |

| | |
|--|---|
| <p>Client Ref. No. _____</p> <p>譲渡証 (Translation/日本語訳)</p> <p>下記に署名した私/私達 (以下譲渡人)、 _____ は、</p> <p>ある発明を創出し、これについて合衆国特許出願又は PCT 国際出願は、</p> <p>(a) <input type="checkbox"/> ここに譲渡人により署名され (全ての発明者は、当該譲渡証に署名した同日に宣誓委任状に署名する)、</p> <p>(b) <input type="checkbox"/> _____ に譲渡人により (それぞれ) 署名され、</p> <p>(c) <input type="checkbox"/> _____ 年 _____ 月 _____ 日に出願され、出願番号 _____ が交付され、</p> <p>(d) <input type="checkbox"/> _____ 年 _____ 月 _____ 日に PCT 国際出願され、出願番号 _____ が交付され、</p> <p>(e) <input type="checkbox"/> _____ 年 _____ 月 _____ 日に米国特許番号 _____ リール番号 _____ フレーム番号 _____ として、</p> <p>その発明は、</p> <p>_____</p> | <p>Attorney Ref. No. <u>0702-000054-US-NP</u></p> <p>Assignment</p> <p>I/We, the undersigned, <u>Hikaru TADANO, Yosuke KONDO and Hiroaki MONMA</u> Hereinafter referred to collectively as Assignor, who have created a certain invention which is the subject of a United States or International application for patent</p> <p>(a) <input type="checkbox"/> executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney);</p> <p>(b) <input type="checkbox"/> executed on _____;</p> <p>(c) <input type="checkbox"/> filed on _____, and assigned Serial No. _____;</p> <p>(d) <input checked="" type="checkbox"/> filed on <u>September 24, 2013</u>, as International Application No. <u>PCT/JP2013/075723</u>;</p> <p>(e) <input type="checkbox"/> US Patent No. _____ issued on _____, and Reel _____, Frame _____; and</p> <p>entitled: <u>SEALING DEVICE</u></p> <p>_____</p> |
| <p>という名称である。そして、ここにその受領を認める対価で譲渡人は、当該発明/出願/特許の存続期間また延長された存続期間満了時まで、合衆国とその属領及び全ての外国に於ける全面的かつ独占的な権利；合衆国法及びその属領の法律、パリ条約、及び全ての外国に於ける法律に基づき優先権を主張する権利；当該譲渡証、将来の販売、過去の侵害から回復する権利、債務を取立てる権利；そして合衆国とその属領及び全ての外国に於いて特許及び出願された及び今後出願される特許に関わる及び当該発明/出願/特許から発生する全ての権利；を日本国 <u>12-15, Shiba Daimon 1-chome, Minato-ku, Tokyo, JAPAN 105-8585</u> に住所を有する <u>NOK CORPORATION</u> (以下譲受人) 及びその後継者に対して、売却、譲渡、移転するものとす</p> | <p>NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy whereof Assignor by these presents does sell, assign and transfer unto hereinafter referred to as Assignee, <u>NOK CORPORATION</u>, a corporation of Japan, at <u>12-15, Shiba Daimon 1-chome, Minato-ku, Tokyo, JAPAN 105-8585</u> in Japan and its successors in interest, the full and exclusive right, title and interest in the United States of America and all foreign countries, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the said invention as described in the aforesaid application, said application for patent and all Letters Patent therefor to be held and enjoyed by Assignee to the full end of the term for which said Letters Patent are granted and any extensions thereof as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made, and</p> |

さらに、譲渡人は、譲受人及びその後継者に、合衆国とその属領及び全ての外国に於いて、仮出願出願、一部継続出願、継続出願、分割出願、差替出願、再発行出願、更新手続、再審査請求、特許期間延長等を含むがこれに限定されないいかなる出願及び出願手続及び当該発明/出願/特許の適切な保護又は維持を目的とする全ての訴訟手続に於いて必要な書類又は証拠を作成する；当該発明/出願/特許の適切な保護又は維持を目的とする全ての訴訟手続に於いて協力し証言する；そして上記は報酬又は無報酬で行うことを承諾する。

さらに、譲渡人は、当該譲渡証に定める事柄と抵触する内容の、譲渡、授権、又は抵当権設定の事実はなく、これからもないことを誓約する。

さらに、当該譲渡証は英語の部分の表現によってのみ解釈されることに同意する。当該譲渡証に定める全ての事柄をここに誓約するため、譲渡人は下記日付で署名する。

| |
|----------------|
| 唯一または第一発明者名 |
| 署名: |
| 日付: _____ |
| 第二共同発明者 (いる場合) |
| 署名: |
| 日付: _____ |
| 第三共同発明者 (いる場合) |
| 署名: |
| 日付: _____ |

the right to recover for past infringements of, or liabilities for, any of the rights relating to any of said applications or patents resulting therefrom;

Assignor hereby covenants and agrees to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

Assignor hereby covenants that no assignment, sale or agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

Assignor hereby covenants that this Assignment is to be construed solely according to the terms of the English language portions thereof. In testimony whereof I/We have hereunto set MY/OUR signature seal on the date indicated below.

| |
|--|
| Full name of sole or first inventor |
| Hikaru TADANO |
| Signature : |
| <i>Hikaru Tadano</i> |
| Dated : <i>Feb 10, 2015</i> |
| Full name of second joint inventor, if any |
| Yosuke KONDO |
| Signature : |
| <i>Yosuke Kondo</i> |
| Dated : <i>Mar 3, 2015</i> |
| Full name of third joint inventor, if any |
| Hiroaki MONMA |
| Signature : |
| <i>Hiroaki Monma</i> |
| Dated : <i>Mar 3, 2015</i> |